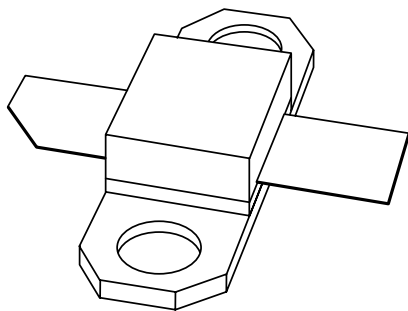


DATA SHEET



BLV2045N UHF power transistor

Preliminary specification
Supersedes data of 1999 May 01

2000 Feb 21

UHF power transistor

BLV2045N

FEATURES

- Emitter ballasting resistors for optimum temperature profile
- Gold metallization ensures excellent reliability
- Internal input and output matching for an easy design of wideband circuits.

APPLICATIONS

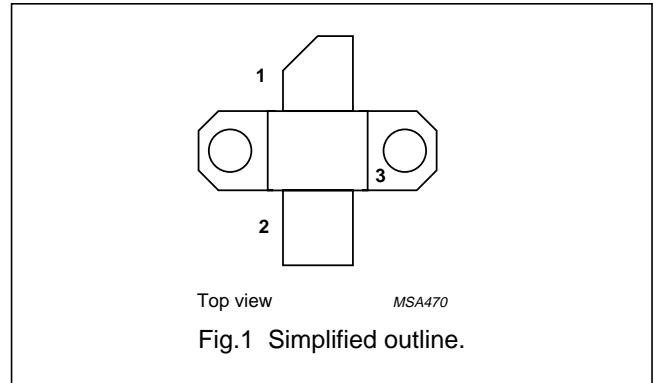
- Common emitter class-AB operation in PCN and PCS applications in the 1800 to 2000 MHz frequency range.

DESCRIPTION

NPN silicon planar UHF power transistor in a 2-lead SOT390A flange package with a ceramic cap. The emitter is connected to the flange.

PINNING - SOT390A

PIN	SYMBOL	DESCRIPTION
1	c	collector
2	b	base
3	e	emitter, connected to flange



QUICK REFERENCE DATA

RF performance at $T_h = 25\text{ °C}$ in a common emitter test circuit.

MODE OF OPERATION	f (MHz)	V_{CE} (V)	P_L (W)	G_p (dB)	η_c (%)	d_{im} (dBc)
CW, class-AB	1990	26	35	typ. 9.5	typ. 43	–
2-tone, class-AB	$f_1 = 1990.0; f_2 = 1990.1$	26	35 (PEP)	≥ 9.5	≥ 33	≤ -30

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	65	V
V_{CEO}	collector-emitter voltage	open base	–	27	V
V_{EBO}	emitter-base voltage	open collector	–	3	V
I_C	collector current (DC)		–	4	A
$I_{C(AV)}$	average collector current		–	4	A
P_{tot}	total power dissipation	$T_{mb} = 25\text{ °C}$	–	125	W
T_{stg}	storage temperature		–65	+150	°C
T_j	operating junction temperature		–	200	°C

WARNING

Product and environmental safety - toxic materials

This product contains beryllium oxide. The product is entirely safe provided that the BeO disc is not damaged. All persons who handle, use or dispose of this product should be aware of its nature and of the necessary safety precautions. After use, dispose of as chemical or special waste according to the regulations applying at the location of the user. It must never be thrown out with the general or domestic waste.

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THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-mb}$	thermal resistance from junction to mounting base	$P_L = 35\text{ W}$; $\eta_C = 40\%$; $T_{mb} = 25\text{ }^\circ\text{C}$	1.4	K/W
$R_{th\ mb-h}$	thermal resistance from mounting base to heatsink		0.4	K/W

CHARACTERISTICS

$T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{(BR)CBO}$	collector-base breakdown voltage	open emitter; $I_C = 20\text{ mA}$	65	–	–	V
$V_{(BR)CEO}$	collector-emitter breakdown voltage	open base; $I_C = 60\text{ mA}$	27	–	–	V
$V_{(BR)EBO}$	emitter-base breakdown voltage	open collector; $I_E = 40\text{ mA}$	3	–	–	V
I_{CES}	collector leakage current	$V_{CE} = 26\text{ V}$; $V_{BE} = 0$	–	–	4	mA
h_{FE}	DC current gain	$V_{CE} = 10\text{ V}$; $I_C = 2\text{ A}$	45	–	100	
C_c	collector capacitance	$V_{CB} = 26\text{ V}$; $I_E = i_e = 0$; $f = 1\text{ MHz}$; note 1	–	t.b.f.	–	pF
C_{re}	feedback capacitance	$V_{CE} = 26\text{ V}$; $I_C = 0$; $f = 1\text{ MHz}$	–	t.b.f.	–	pF

Note

1. Capacitance of die only.

APPLICATION INFORMATION

RF performance at $T_h = 25\text{ }^\circ\text{C}$ in a common emitter test circuit.

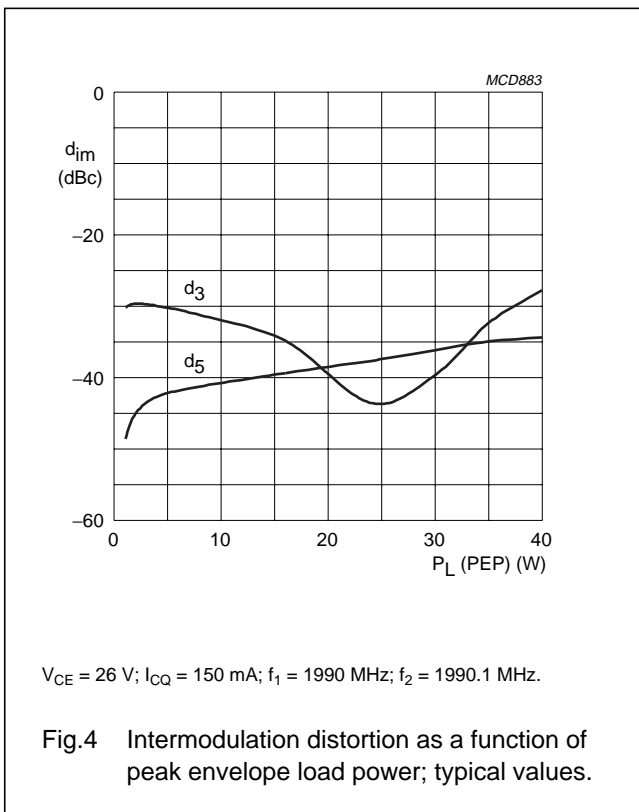
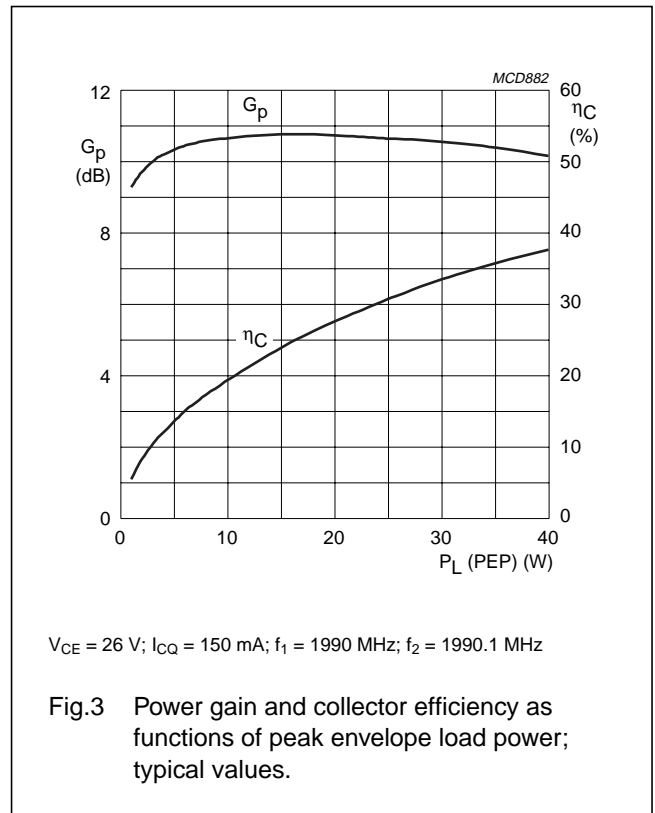
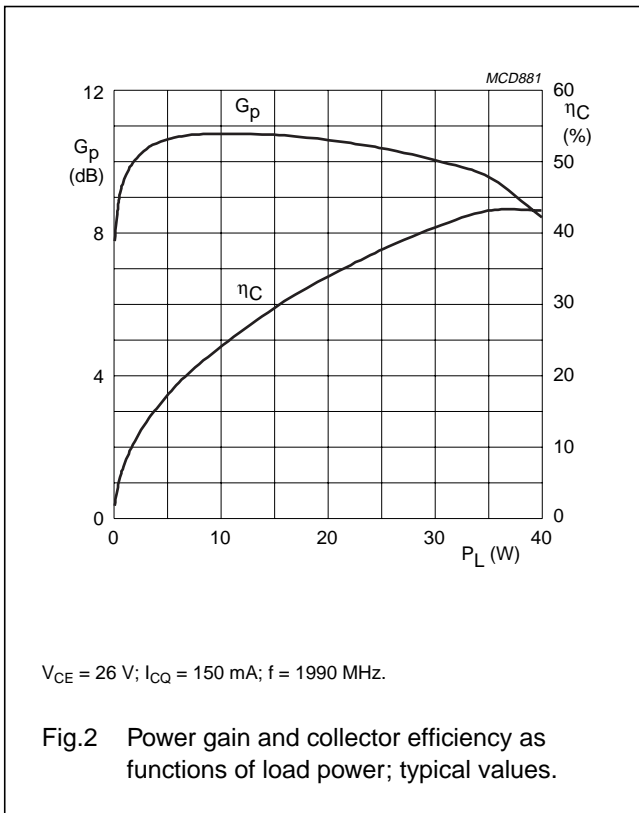
MODE OF OPERATION	f (MHz)	V_{CE} (V)	I_{CQ} (mA)	P_L (W)	G_p (dB)	η_C (%)	d_{im} (dBc)
CW, class-AB	1990	26	150	35	typ. 9.5	typ. 43	–
2-tone, class-AB	$f_1 = 1990.0$; $f_2 = 1990.1$	26	150	35 (PEP)	≥ 9.5 typ. 10.2	≥ 33 typ. 35	≤ -30 typ. -32

Ruggedness in class-AB operation

The BLV2045N is capable of withstanding a load mismatch corresponding to $V_{SWR} = 3 : 1$ through all phases under the following conditions: $f_1 = 1990.0\text{ MHz}$; $f_2 = 1990.1\text{ MHz}$; $V_{CE} = 26\text{ V}$; $I_{CQ} = 150\text{ mA}$; $P_L = 35\text{ W}$ (PEP); $T_{mb} = 25\text{ }^\circ\text{C}$.

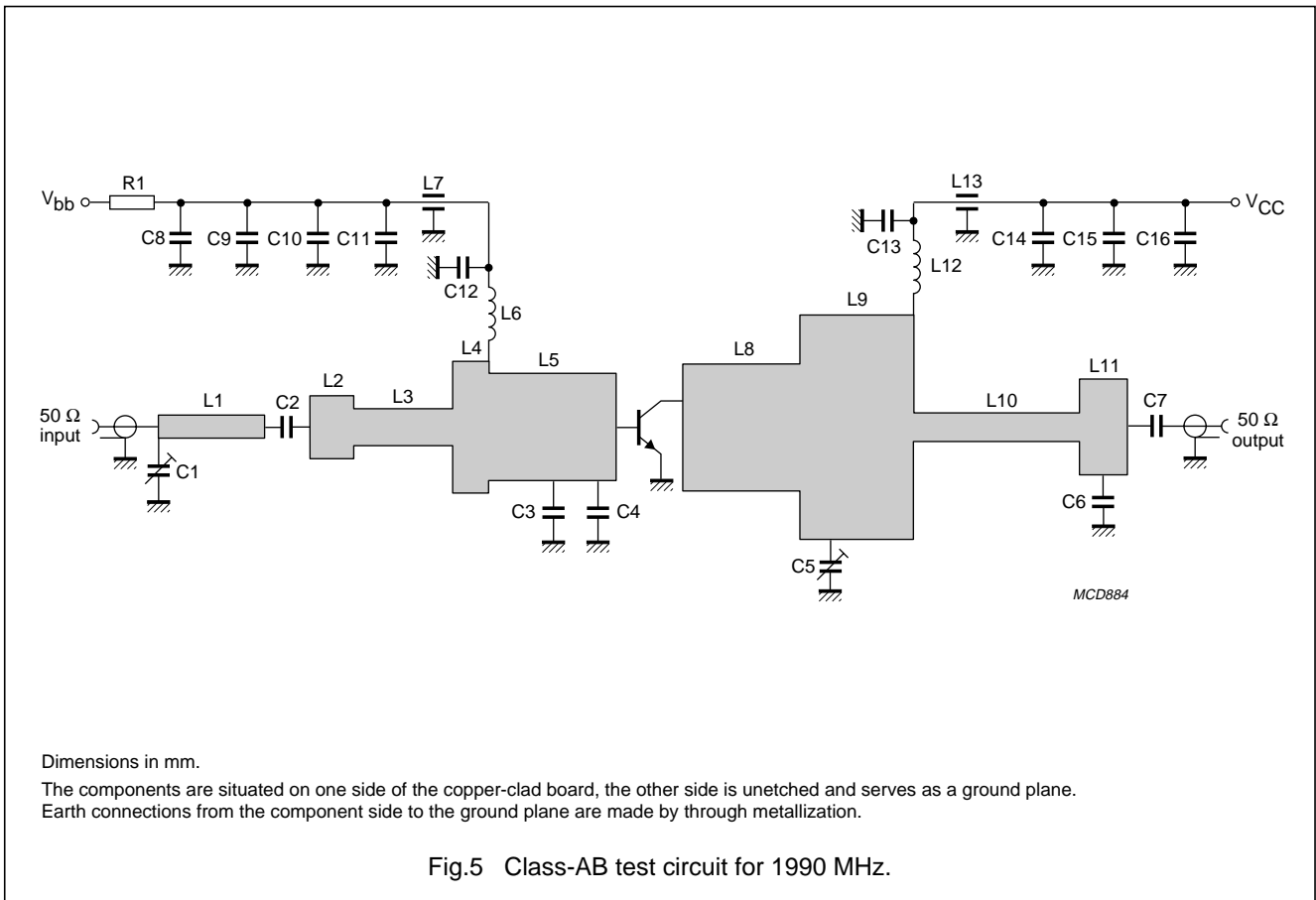
UHF power transistor

BLV2045N



UHF power transistor

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UHF power transistor

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List of components (see Figs 5 and 6)

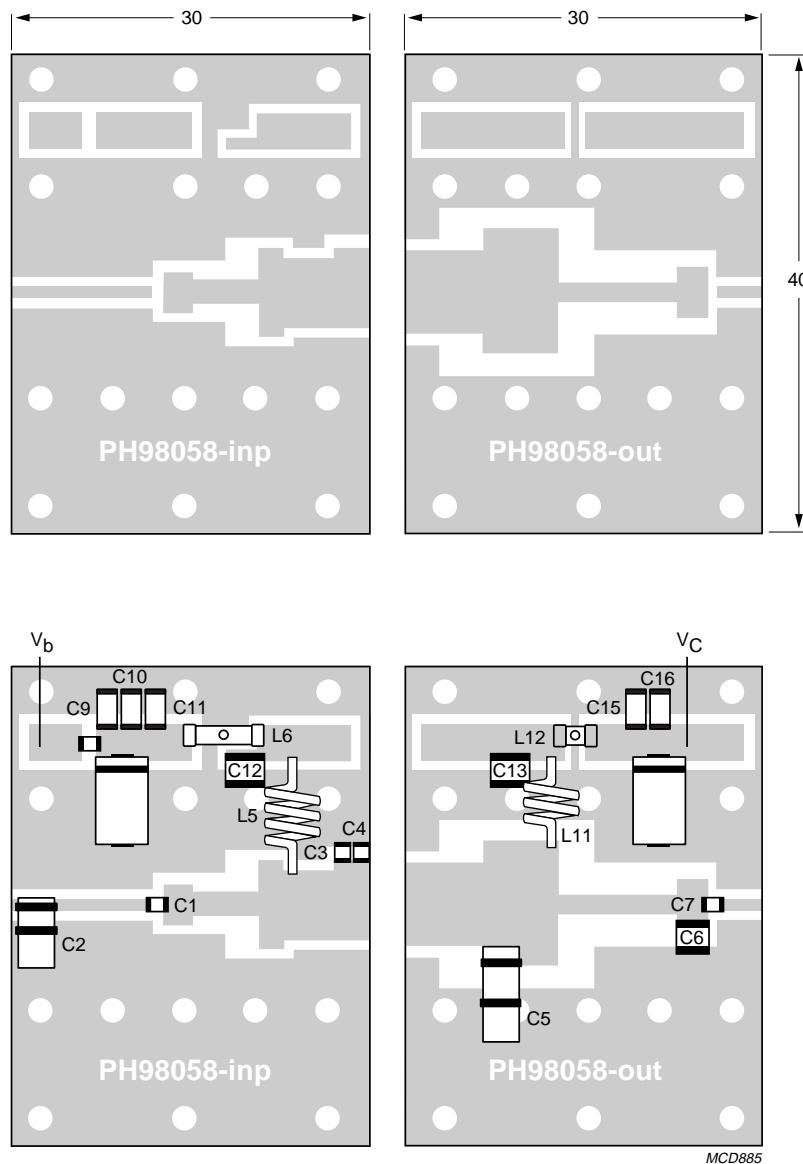
COMPONENT	DESCRIPTION	VALUE	DIMENSIONS
C1	Tekelec variable capacitor; type AT37281	0.4 to 2.5 pF	
C2, C7	multilayer ceramic chip capacitor; note 1	30 pF	
C3	multilayer ceramic chip capacitor; note 2	2.4 pF	
C4	multilayer ceramic chip capacitor; note 2	1.8 pF	
C5	Tekelec variable capacitor; type AT37271	0.6 to 4.5 pF	
C6	multilayer ceramic chip capacitor; note 2	1.3 pF	
C8, C14	tantalum SMD capacitor	35 V; 10 μ F	
C9, C10, C11, C15, C16	multilayer ceramic chip capacitor	100 nF	
C12, C13	multilayer ceramic chip capacitor; note 2	20 pF	
L1	stripline; note 3	50 Ω	8 x 1 mm
L2	stripline; note 3	20.5 Ω	2.5 x 3.5 mm
L3	stripline; note 3	29.8 Ω	5.6 x 2.1 mm
L4	stripline; note 3	11 Ω	2.0 x 7.4 mm
L5	stripline; note 3	13.2 Ω	7.2 x 6.0 mm
L6	5 turns enamelled 1 mm copper wire		int. dia. = 3.3 mm; length = 6 mm
L7	EMI filter; type NFM61RH20T332	3300 pF	
L8	stripline; note 3	11.5 Ω	6.6 x 7.1 mm
L9	stripline; note 3	6.9 Ω	6.4 x 12.6 mm
L10	stripline; note 3	35.8 Ω	9.9 x 1.6 mm
L11	stripline; note 3	14.4 Ω	2.7 x 5.4 mm
L12	2 turns enamelled 1 mm copper wire		int. dia. = 3.3 mm; length = 2.5 mm
L13	EMI filter; type NFM60RH20T152	1500 pF	
R1	chip resistor	2.2 Ω	

Notes

1. American Technical Ceramics type 100A or capacitor of same quality.
2. American Technical Ceramics type 100B or capacitor of same quality.
3. The striplines are on a double copper-clad printed-circuit board: $\epsilon_r = 6.15$; thickness 0.64mm.

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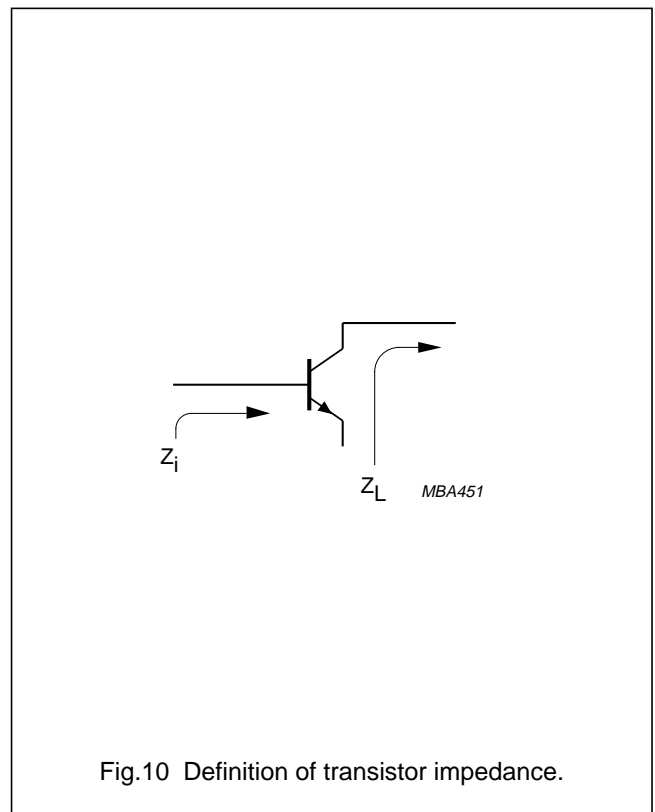
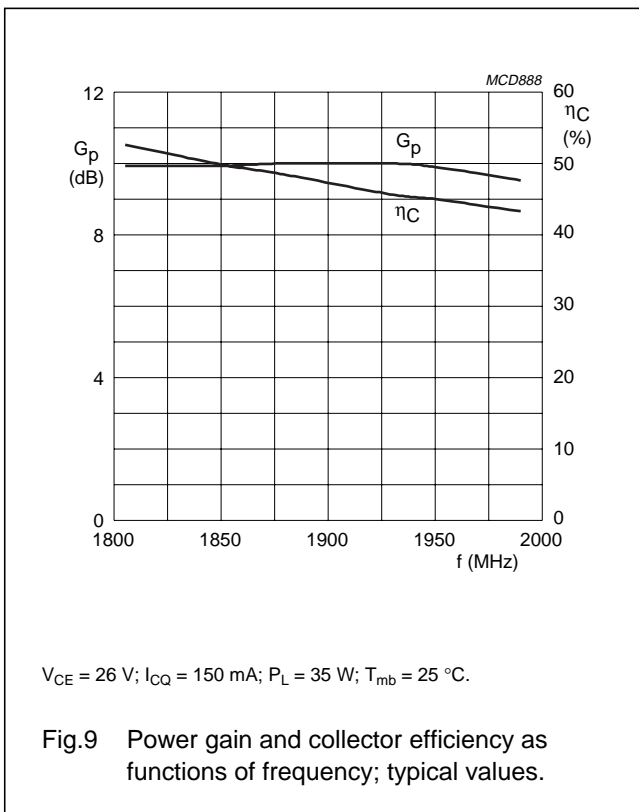
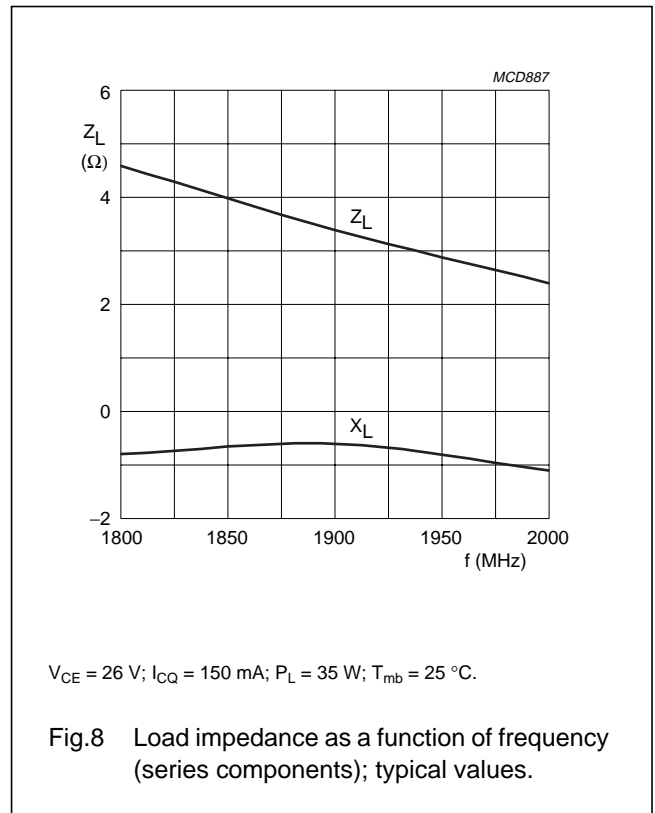
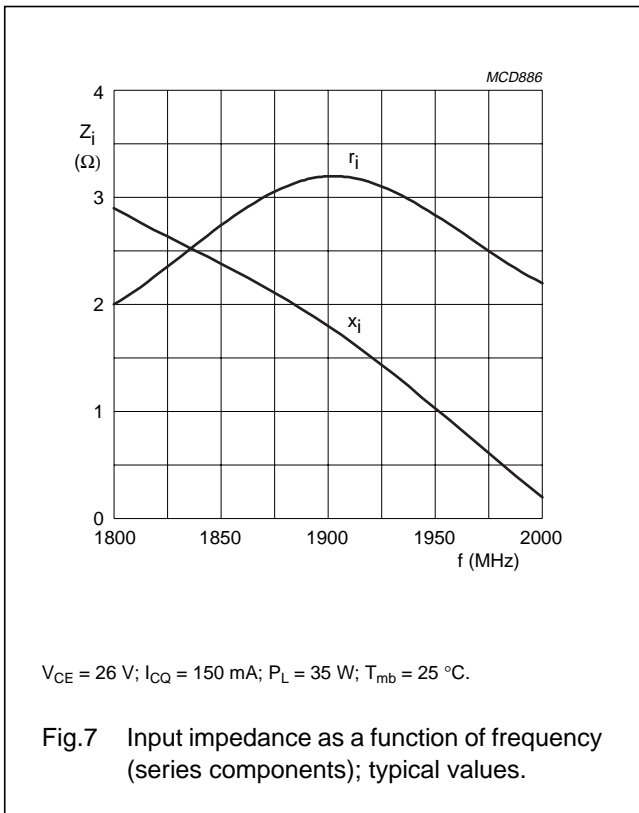
Dimensions in mm.

The components are situated on one side of the copper-clad board, the other side is unetched and serves as a ground plane. Earth connections from the component side to the ground plane are made by through metallization.

Fig.6 Printed-circuit board and component layout for class-AB broadband test circuit.

UHF power transistor

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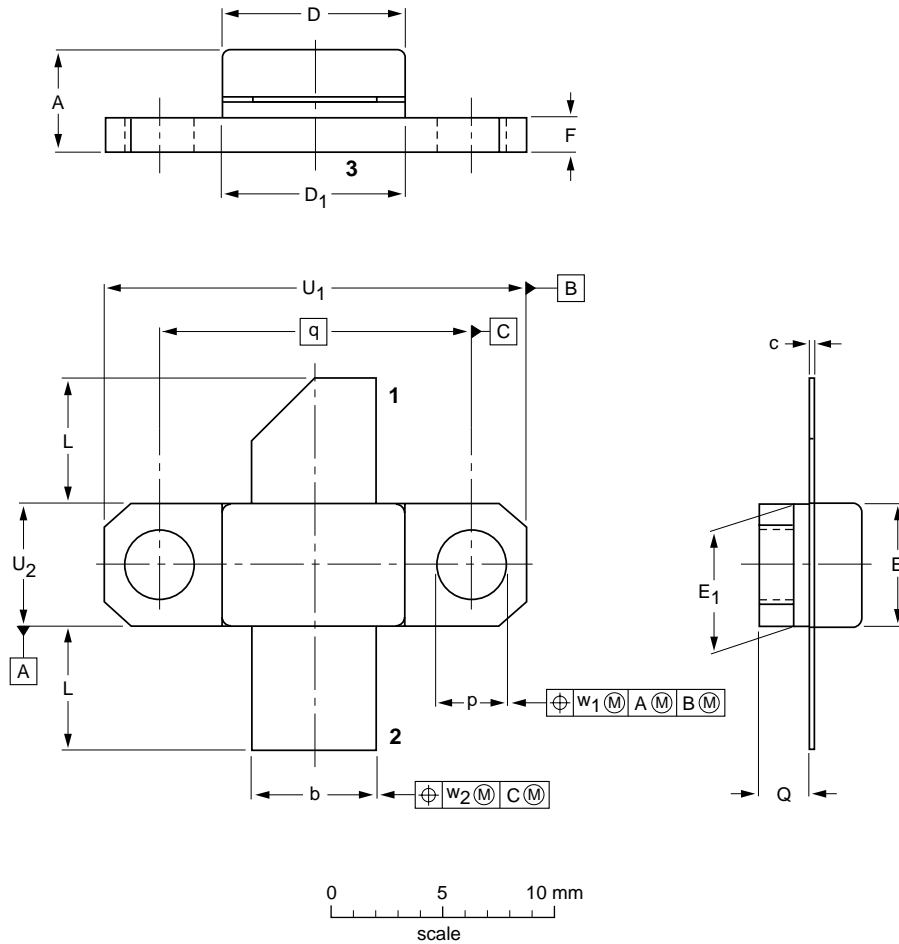
UHF power transistor

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PACKAGE OUTLINE

Flanged ceramic package; 2 mounting holes; 2 leads

SOT390A



DIMENSIONS (millimetre dimensions are derived from the original inch dimensions)

UNIT	A	b	c	D	D ₁	E	E ₁	F	L	p	Q	q	U ₁	U ₂	w ₁	w ₂
mm	5.03 4.22	5.72 5.46	0.16 0.10	8.18 8.08	8.26 8.00	6.40 6.30	6.43 6.17	1.66 1.39	6.10 5.33	3.43 3.17	2.32 2.00	14.22	19.03 18.77	6.43 6.17	0.25	0.51
inches	0.198 0.166	0.225 0.215	0.006 0.004	0.322 0.318	0.325 0.315	0.252 0.248	0.253 0.243	0.065 0.055	0.24 0.21	0.135 0.125	0.091 0.079	0.560	0.749 0.739	0.253 0.243	0.010	0.020

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT390A						99-03-29

UHF power transistor

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DEFINITIONS

Data Sheet Status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

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NOTES

Philips Semiconductors – a worldwide company

Argentina: see South America

Australia: 3 Figtree Drive, HOMEBUSH, NSW 2140,
Tel. +61 2 9704 8141, Fax. +61 2 9704 8139

Austria: Computerstr. 6, A-1101 WIEN, P.O. Box 213,
Tel. +43 1 60 101 1248, Fax. +43 1 60 101 1210

Belarus: Hotel Minsk Business Center, Bld. 3, r. 1211, Volodarski Str. 6,
220050 MINSK, Tel. +375 172 20 0733, Fax. +375 172 20 0773

Belgium: see The Netherlands

Brazil: see South America

Bulgaria: Philips Bulgaria Ltd., Energoproject, 15th floor,
51 James Bourchier Blvd., 1407 SOFIA,
Tel. +359 2 68 9211, Fax. +359 2 68 9102

Canada: PHILIPS SEMICONDUCTORS/COMPONENTS,
Tel. +1 800 234 7381, Fax. +1 800 943 0087

China/Hong Kong: 501 Hong Kong Industrial Technology Centre,
72 Tat Chee Avenue, Kowloon Tong, HONG KONG,
Tel. +852 2319 7888, Fax. +852 2319 7700

Colombia: see South America

Czech Republic: see Austria

Denmark: Sydhavnsgade 23, 1780 COPENHAGEN V,
Tel. +45 33 29 3333, Fax. +45 33 29 3905

Finland: Sinikalliontie 3, FIN-02630 ESPOO,
Tel. +358 9 615 800, Fax. +358 9 6158 0920

France: 51 Rue Carnot, BP317, 92156 SURESNES Cedex,
Tel. +33 1 4099 6161, Fax. +33 1 4099 6427

Germany: Hammerbrookstraße 69, D-20097 HAMBURG,
Tel. +49 40 2353 60, Fax. +49 40 2353 6300

Hungary: see Austria

India: Philips INDIA Ltd, Band Box Building, 2nd floor,
254-D, Dr. Annie Besant Road, Worli, MUMBAI 400 025,
Tel. +91 22 493 8541, Fax. +91 22 493 0966

Indonesia: PT Philips Development Corporation, Semiconductors Division,
Gedung Philips, Jl. Buncit Raya Kav.99-100, JAKARTA 12510,
Tel. +62 21 794 0040 ext. 2501, Fax. +62 21 794 0080

Ireland: Newstead, Clonskeagh, DUBLIN 14,
Tel. +353 1 7640 000, Fax. +353 1 7640 200

Israel: RAPAC Electronics, 7 Kehilat Saloniki St, PO Box 18053,
TEL AVIV 61180, Tel. +972 3 645 0444, Fax. +972 3 649 1007

Italy: PHILIPS SEMICONDUCTORS, Via Casati, 23 - 20052 MONZA (MI),
Tel. +39 039 203 6838, Fax +39 039 203 6800

Japan: Philips Bldg 13-37, Kohnan 2-chome, Minato-ku,
TOKYO 108-8507, Tel. +81 3 3740 5130, Fax. +81 3 3740 5057

Korea: Philips House, 260-199 Itaewon-dong, Yongsan-ku, SEOUL,
Tel. +82 2 709 1412, Fax. +82 2 709 1415

Malaysia: No. 76 Jalan Universiti, 46200 PETALING JAYA, SELANGOR,
Tel. +60 3 750 5214, Fax. +60 3 757 4880

Mexico: 5900 Gateway East, Suite 200, EL PASO, TEXAS 79905,
Tel. +9-5 800 234 7381, Fax +9-5 800 943 0087

Middle East: see Italy

Netherlands: Postbus 90050, 5600 PB EINDHOVEN, Bldg. VB,
Tel. +31 40 27 82785, Fax. +31 40 27 88399

New Zealand: 2 Wagener Place, C.P.O. Box 1041, AUCKLAND,
Tel. +64 9 849 4160, Fax. +64 9 849 7811

Norway: Box 1, Manglerud 0612, OSLO,
Tel. +47 22 74 8000, Fax. +47 22 74 8341

Pakistan: see Singapore

Philippines: Philips Semiconductors Philippines Inc.,
106 Valero St. Salcedo Village, P.O. Box 2108 MCC, MAKATI,
Metro MANILA, Tel. +63 2 816 6380, Fax. +63 2 817 3474

Poland: Al.Jerozolimskie 195 B, 02-222 WARSAW,
Tel. +48 22 5710 000, Fax. +48 22 5710 001

Portugal: see Spain

Romania: see Italy

Russia: Philips Russia, Ul. Usatcheva 35A, 119048 MOSCOW,
Tel. +7 095 755 6918, Fax. +7 095 755 6919

Singapore: Lorong 1, Toa Payoh, SINGAPORE 319762,
Tel. +65 350 2538, Fax. +65 251 6500

Slovakia: see Austria

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South Africa: S.A. PHILIPS Pty Ltd., 195-215 Main Road Martindale,
2092 JOHANNESBURG, P.O. Box 58088 Newville 2114,
Tel. +27 11 471 5401, Fax. +27 11 471 5398

South America: Al. Vicente Pinzon, 173, 6th floor,
04547-130 SÃO PAULO, SP, Brazil,
Tel. +55 11 821 2333, Fax. +55 11 821 2382

Spain: Balmes 22, 08007 BARCELONA,
Tel. +34 93 301 6312, Fax. +34 93 301 4107

Sweden: Kottbygatan 7, Akalla, S-16485 STOCKHOLM,
Tel. +46 8 5985 2000, Fax. +46 8 5985 2745

Switzerland: Allmendstrasse 140, CH-8027 ZÜRICH,
Tel. +41 1 488 2741 Fax. +41 1 488 3263

Taiwan: Philips Semiconductors, 6F, No. 96, Chien Kuo N. Rd., Sec. 1,
TAIPEI, Taiwan Tel. +886 2 2134 2886, Fax. +886 2 2134 2874

Thailand: PHILIPS ELECTRONICS (THAILAND) Ltd.,
209/2 Sanpavuth-Bangna Road Prakanong, BANGKOK 10260,
Tel. +66 2 745 4090, Fax. +66 2 398 0793

Turkey: Yukari Dudullu, Org. San. Blg., 2.Cad. Nr. 28 81260 Umraniye,
ISTANBUL, Tel. +90 216 522 1500, Fax. +90 216 522 1813

Ukraine: PHILIPS UKRAINE, 4 Patrice Lumumba str., Building B, Floor 7,
252042 KIEV, Tel. +380 44 264 2776, Fax. +380 44 268 0461

United Kingdom: Philips Semiconductors Ltd., 276 Bath Road, Hayes,
MIDDLESEX UB3 5BX, Tel. +44 208 730 5000, Fax. +44 208 754 8421

United States: 811 East Arques Avenue, SUNNYVALE, CA 94088-3409,
Tel. +1 800 234 7381, Fax. +1 800 943 0087

Uruguay: see South America

Vietnam: see Singapore

Yugoslavia: PHILIPS, Trg N. Pasica 5/v, 11000 BEOGRAD,
Tel. +381 11 3341 299, Fax.+381 11 3342 553

For all other countries apply to: Philips Semiconductors,
International Marketing & Sales Communications, Building BE-p, P.O. Box 218,
5600 MD EINDHOVEN, The Netherlands, Fax. +31 40 27 24825

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